

U.S. Patent Application of Tokmulin et al.
Serial No.: 08/860,763
Art Unit: 1763

IN THE SPECIFICATION:

Please replace the specification as filed with the Substitute Specification submitted herewith. Submitted with this Amendment is a copy identical in content and formatting to the original specification, but marked with additions and deletions to indicate the changes that applicants have made to the original specification as filed. Also enclosed is a copy of the revised specification in "final" form with the revisions absorbed into a "clean" text no longer marked for the reader. This also constitutes a statement that the Substitute Specification has been compared with the original specification as filed and, with the exception of the revisions or amendments to the original specification made herein, the two specifications are the same and contain no new matter.

IN THE CLAIMS:

Please cancel claim 1, without prejudice, and add new claims 2-13 as follows.

A'
Sub
C1

2. A device for treating wafers with a plasma jet, comprising a plasma jet generator; gas supplying means; a set of holders for wafers to be treated, said holders having a drive for effecting angular displacement thereof and for facing a generator plasma jet; each of the holders being made in the form of a horizontal platform mounted for rotation about an axis passing through a geometric center thereof and perpendicular to a plane of said platform; said plasma jet and wafer holders being displaced with respect to each other and may be in or out of contact with each other, a plasma jet generator located such that a plasma jet is directed upwardly in respect of a